

<u>Atty Docket No.</u> MICS:0045-1(01-0354) <u>Application No.</u> 10/723,792

Filing Date: 11/24/2003 Applicant(s): David J. Corisis Submitted: 03/03/2004

Page 1 of 5

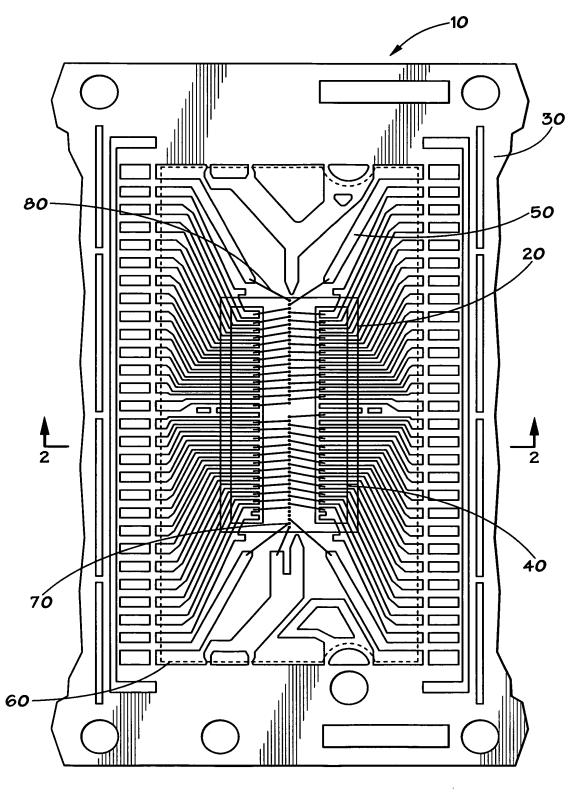


FIG. 1

Atty Docket No. MICS:0045-1(01-0354)
Application No. 10/723,792
Filing Date: 11/24/2003
Applicant(s): David J. Corisis
Submitted: 03/03/2004

 Φ

Page 2 of 5

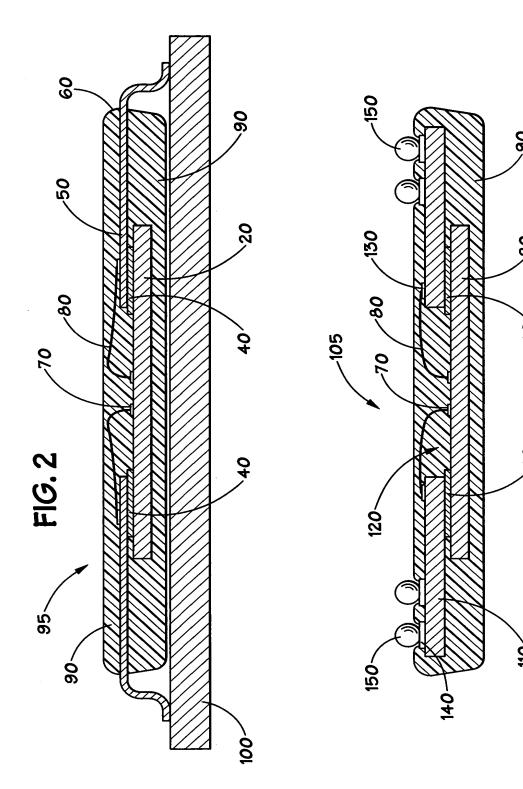


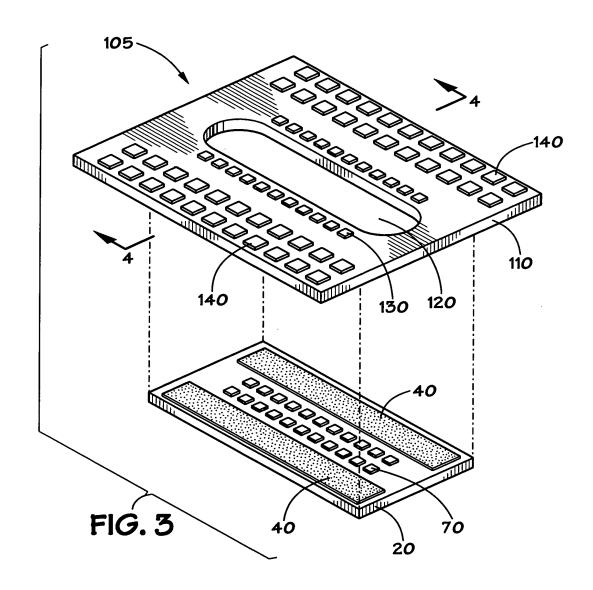
FIG. 4

Atty Docket No. MICS:0045-1(01-0354)

Application No. 10/723,792 Filing Date: 11/24/2003
Applicant(s): David J. Corisis
Submitted: 03/03/2004

 Φ

Page 3 of 5

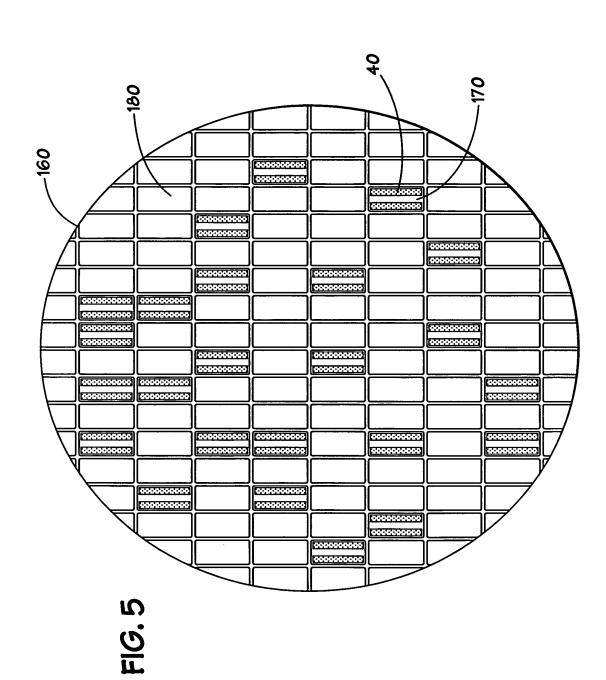


Atty Docket No. MICS:0045-1(01-0354)

Application No. 10/723,792 Filing Date: 11/24/2003 Applicant(s): David J. Corisis Submitted: 03/03/2004

 Φ

Page 4 of 5



Application No. 10/723,792 Filing Date: 11/24/2003 Applicant(s): David J. Corisis Submitted: 03/03/2004 Page 5 of 5 -200 **WAFER FABRICATION** -205 **WAFER PROBE GENERATE GOOD DIE MAP** -210 **GRIND WAFER TO DESIRED THICKNESS** -215 ATTACH TAPE TO **GOOD DIE SITE ACCORDING TO WAFER MAP** -220 DIE **SINGULATION** -225 ATTACH DIE TO LEADFRAME / SUBSTRATE -230 FINAL ASSEMBLY **WIRE BOND ENCAPSULATION** PLATE / BALL ATTACH **SINGULATION**

Atty Docket No. MICS:0045-1(01-0354)

4

FIG. 6